RESIN MOLDING APPARATUS AND METHOD FOR MANUFACTURING RESIN MOLDED PRODUCT

ABSTRACT

According to embodiments of the present invention, a resin molding apparatus is provided. The resin molding apparatus includes an upper mold having a holding surface configured to hold a molding object on a lower side thereof, a lower mold disposed to face the upper mold and having a cavity, a first molding object suctioning mechanism provided in the holding surface and configured to cause a molding object to be suctioned onto the holding surface by suctioning a gas using a vacuum pump, and a second molding object suctioning mechanism provided in the holding surface and configured to cause a molding object to be suctioned onto the holding surface in addition to the suctioning of the gas using the vacuum pump. According to further embodiments of the present invention, a method for manufacturing a resin molded product using the resin molding apparatus according to various embodiments is also provided.

FIG. 7B